ASSOCIATION CONNECTIN	Material Composi © Copyright 2005. IPC, international and Pan-Ar	Bannockb	urn, Illinois. A	ll rights reserved un ntions.	nder both	This docume level parts, t	ent is a declaration	ion of the su encompasse	ubstances s all lower	within the manufactur level materials for w	er listed i hich the r	tem. Note: if nanufacturer	f the item is an as has engineering	ssembly with low responsibility.
1752-21.1					Form Type Distribute	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					als and Mfg Information			
Supplier Inform	nation													
Company name*			Company unique ID				Unique ID Authority				Response Date*			
onsemi											2024-04-27			
Contact Name			Title - Contact				Phone - Contact*				Email - Contact*			
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
Authorized Representative*			Title - Representative				Phone - Representative*			Email - Representative*				
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
Request	Requester Item Number Mfr Item		n Number Mfr Item Name				Effective Date Version Manufacturing Site		Ianufacturing Site		Weight*	UOM	Unit Type	
		QT6810 RI		RFIC 2.4 GHz			2024-04-27		К	KR9		96.499	mg	Each
<b>Anufacturing</b>	Proccess Information	n												
Terminal Plating / Grid Array Material Terr		rminal Base Alloy J-STD-020 MSI		L Rating	Peak Process Body Temperate		emperatur	e Max Time at Peak	Tempera	ture Numb	er of Reflow Cyc	cles		
SnAgCu CU A			U Alloy 3				260 C 30				seconds 3			
omments														
TTENTION: MS	L 3 Rated item requires Ba	ake and D	ry Pack (after	electrical test)										
or more informati	ion regarding material con	nposition	please refer to	page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	oHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl hthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).									
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and co for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of					
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted						
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all					
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the					
Supplier Digital Signature Ra	stislav Drska	Le								

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	10.0	mg	Supplier	Silicon (Si)	7440-21-3		10	mg
Mold Compound-Black	35.49	mg	Supplier	Carbon Black (C)	1333-86-4		0.1775	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		31.4087	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		1.952	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		1.952	mg
Solder Ball	10.49	mg	Supplier	Silver (Ag)	7440-22-4		0.3147	mg
			Supplier	Tin (Sn)	7440-31-5		10.1228	mg
			Supplier	Copper (Cu)	7440-50-8		0.0524	mg
Solder Mask	3.325	mg	Supplier	Talc	14807-96-6		0.1663	mg
			Supplier	Naphthalene	91-20-3		0.0665	mg
			Supplier	Phosphinoxide Derivative	Proprietary Data		0.1663	mg
			Supplier	2-(2-methoxypropoxy)propanol	34590-94-8		0.399	mg
			Supplier	4,4'-Bis(2,3-epoxypropoxy)-3,3',5,5'- tetramethylbiphenyl	85954-11-6		0.7648	mg
			Supplier	Solvent Naphtha (Solvent oil)	64742-94-5		0.4655	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7		1.2967	mg
ubstrate Copper Foil	1.26	mg	Supplier	Copper (Cu)	7440-50-8		1.26	mg
Substrate - Core Material	13.94	mg		Epoxy resin	proprietary data		3.0208	mg
			Supplier	Fiber Glass (SiO2)	65997-17-3		10.9192	mg
Substrate Plating-Cu	21.994	mg	Supplier	Copper (Cu)	7440-50-8		21.994	mg